



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Ball et al.

**Serial No.:** 09/736,795

**Filed:** December 14, 2000

**For:** METHOD OF DISPOSING  
CONDUCTIVE BUMPS ONTO A  
SEMICONDUCTOR DEVICE

**Confirmation No.:** 6757

**Examiner:** E. Pert

**Group Art Unit:** 2829

**Attorney Docket No.:** 2269-3817.1US  
(97-1350.01/US)

**Notice of Allowance Mailed:**

April 2, 2004

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**Person making Deposit:** Christopher Haughton

*Please  
enter.  
Thanks.  
EP 11-20-04*

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** begin on page 3 of this paper.